



<b>Title of Change:</b>	Change Lead frame N03503D003 to Lead frame N03503D005 For TSOP6 – NLAST4599DDTT1G, NLAS4599DDTT1G
<b>Proposed first ship date:</b>	19 June 2015
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <ricardo.avila@onsemi.com>
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or jose.aguilar@onsemi.com>.
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.

<b>Change Part Identification:</b>	Date Code 2015, week 24 or later will contain this change.
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<b>Change category(s):</b> <input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change			<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Material Change	<input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
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<b>Sites Affected:</b> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	<u>Site 1</u> ON Seremban, Malaysia	<u>Site 2</u>
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**Description and Purpose:**

ON Semiconductor is pleased to announce the introduction of a new lead frame for the products listed using the TSOP-6 Package Case Outline 318G-02.

The flag and Pin 3 are connected on this lead frame, setting the die bond pad, the substrate, flag and pin at the same potential (Gnd). There are no changes to Electrical performance, Case outline or Foot print.

**Reliability Data Summary:**

#	Test	Name	Test Conditions	End Point Req's	Test Results (rej/ss)	
					Read Point	Lot A
1	PC	MSL1 preconditioning	3 IR @ 260 °C	c = 0, Room		all
2	TC-PC	Temperature Cycle	-65/+150 C	c = 0, Room	1000cyc	0/84
3	HAST-PC	Highly Accelerated Stress Test	Temp= +130°C, RH=85%, p = 18.8 psig, bias	c = 0, Room	96hrs	0/84
4	UHAST-PC	Unbiased Highly Accelerated Stress Test	Temp= +130°C, RH=85%, p = 18.8 psig, unbiased	c = 0, Room	96hrs	0/84

Based on the results presented here, device NLAS4599DDTT1G housed in package TSOP6 with lead frame N03503D005, using technology TS60, assembled and tested at Seremban, Malaysia has met and exceeded the requirements and it is considered qualified per ON Semiconductor's Product Qualification Specifications, 12MSB17722C.



**Electrical Characteristic Summary:**

Electrical Characteristics are not impacted

**List of Affected Standard Parts:**

NLAST4599DTT1G

NLAS4599DTT1G